DESCRIPTION

~~DOUBLE SURFACE POLISHING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to a double-side polishing method of simultaneously polishing both surfaces of a wafer with a carrier for double-side polishing.

BACKGROUND ART

[0002]

In simultaneous polishing of both surfaces of a wafer such as double-side polishing, the wafer is held with a carrier for use in a double-side polishing apparatus.

FIG. 8 is a schematic diagram for explanation of wafer double-side polishing with a common double-side polishing apparatus conventionally used. As shown in FIG. 8, the carrier 102 of the double-side polishing apparatus 101 has a holding hole 104 for holding a wafer W. The carrier 102 is formed with a thickness thinner than that of the wafer W.

[0003]

The wafer W is inserted and held in the holding hole 104. The upper and lower surfaces of the wafer W are interposed between polishing pads 107, which are disposed on the opposing sides of an upper turn table 105 and a lower turn table 106.

The carrier 102 is engaged with a sun gear 108 and an internal gear 109 and thereby rotated and revolved by the rotation of the sun gear 108. The upper turn table

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